

a printed circuit board covering the entire first layer and the hollowed out portion and having an opposing surface provided opposite the face of the piezoelectric substrate with the first layer disposed between said opposing surface and said face, said opposing surface having an area equal to an area of said face of said piezoelectric substrate, said printed circuit board further having external conductive contacts; and

conductive via holes going through the first layer and the printed circuit board and connecting the internal and external conductive contacts,

wherein the first layer completely surrounds each of the conductive via holes.

#### REMARKS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-6 are pending in the present application. Claims 7-14 have been cancelled, and Claim 1 has been amended by the present amendment.

In the outstanding Office Action, Claims 1-6 were rejected under 35 U.S.C. § 103(a) as unpatentable over Takoshima in view of Onishi et al ('142), Tsuji et al or Onishi et al ('368) or vice versa, which is respectfully traversed.

Applicants thank the Examiner for the courtesy of an interview extended to Applicants' representative on February 27, 2002. During the interview, the differences between the present invention and the applied art were discussed. No agreement was reached pending the Examiner's further review when a response is filed. Arguments presented during the interview are reiterated below.

Claim 1 is directed to a surface acoustic wave component including a first layer located on a face of a piezoelectric substrate and having a hollowed out portion at least to a